

Amendments to the Claims

1-22. (Cancelled)

23. (New) An optical information recording medium capable of reproducing information using laser light, said optical information recording medium comprising:

 a substrate;

 a recording layer;

 a reflective layer provided between said substrate and said recording layer;

 a cover layer;

 a reflective layer-side dielectric layer disposed between said reflective layer and said recording layer; and

 an incident light-side dielectric layer disposed between said recording layer and said cover layer,

 wherein said reflective layer is formed as a film directly on said substrate, and is an aluminum alloy containing at least 1 atom percent and no more than 5 atom percent nickel.

24. (New) The optical information recording medium according to Claim 23, wherein a thickness of said reflective layer is at least 20 nm and no more than 300 nm.

25. (New) The optical information recording medium according to Claim 23, wherein said reflective layer-side dielectric layer contains sulfur.

26. (New) The optical information recording medium according to Claim 23, wherein a main component of said reflective layer-side dielectric layer is ZnS or an oxide, main components of said recording layer are germanium and antimony, or germanium, bismuth, and tellurium, and a main component of said incident light-side dielectric layer is ZnS or an oxide.

27. (New) The optical information recording medium according to Claim 23, wherein a

thickness of said reflective layer-side dielectric layer is at least 15 nm and no more than 50 nm, a thickness of said recording layer is at least 5 nm and no more than 15 nm, and a thickness of said incident light-side dielectric layer is at least 10 nm and no more than 100 nm.

28. (New) The optical information recording medium according to Claim 23, wherein said reflective layer-side dielectric layer is in contact with said reflective layer.

29. (New) A method for manufacturing an optical information recording medium comprising:

forming a reflective layer on a substrate;

forming a recording layer on the substrate; and

forming a cover layer, a reflective layer-side dielectric layer disposed between the reflective layer and the recording layer, and an incident light-side dielectric layer disposed between the recording layer and the cover layer,

wherein the reflective layer is formed as a film directly on the substrate and said forming of the reflective layer includes using a sputtering target comprising an aluminum alloy containing at least 1 atom percent and no more than 5 atom percent nickel, and

wherein the reflective layer is formed between the substrate and the recording layer.